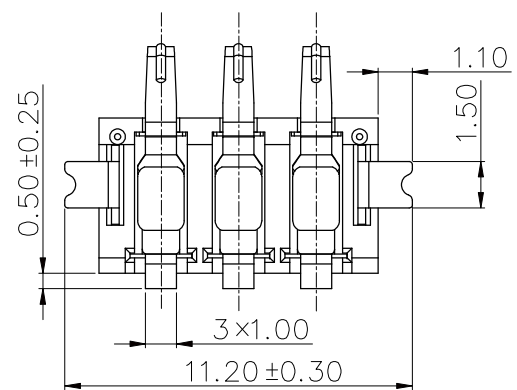
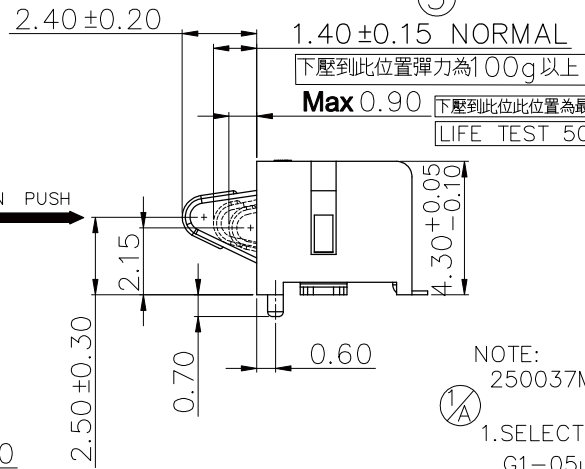
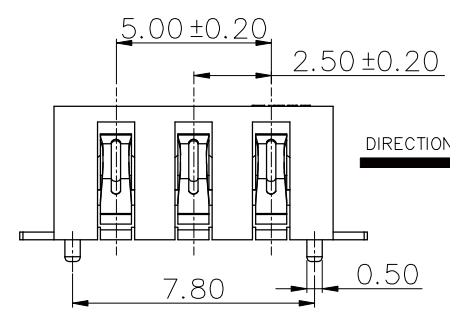
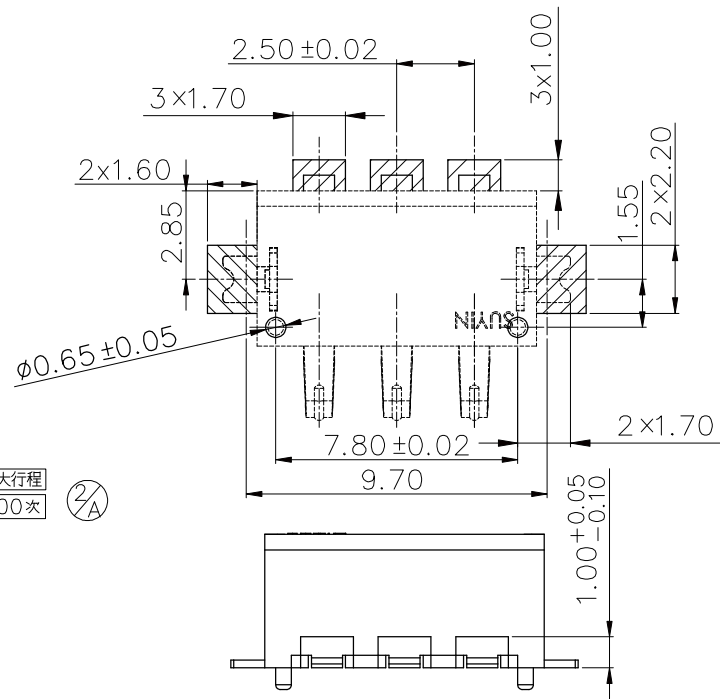
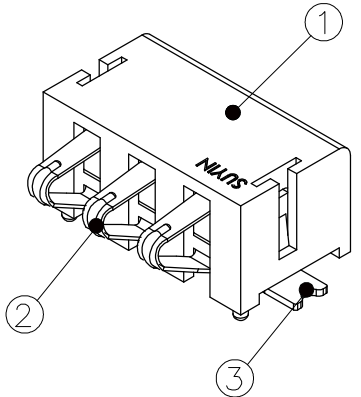
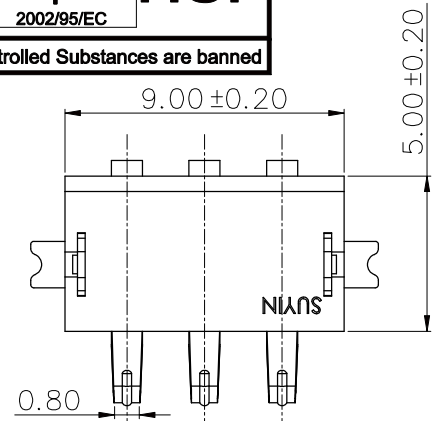


Pb Process Capable
RoHS Compliant
 2002/95/EC
HSF

Level-1 Controlled Substances are banned

RECOMMENDED P.C.B LAYOUT (COMPONENT SIDE)
 P.C.B THICKNESS=0.90mm(TOLERANCE=±0.05)



NOTE:
 250037MB003G_12ZL

1. SELECTIVE PLATING
- G1-05u" GOLD OVER NICKEL.
 - G2-GOLD FLASH OVER 30 u"MIN. NICKEL.
 - G3-10u" GOLD OVER NICKEL.
 - G4-15u" GOLD OVER NICKEL.
 - G5-30u" GOLD OVER NICKEL.
 - G6-50u" GOLD OVER NICKEL.

NOTE:
 NORMAL FORCE 100g MIN~250gMAX
 PER PIN (STROKE=1.50mm)

NO.	DESCRIPTION	MATERIAL	COLOR	REMARK
3	FORK	METAL		TIN PLATED OVER NICKEL
2	TERMINAL	COPPER ALLOY		GOLD PLATED OVER NICKEL
1	HOUSING	HIGH TEMP PLASTIC	BLACK	UL94V-0

CUSTOMER COPY		TITLE: 2.50mm PITCH SPRING BATTERY SMD TYPE	
		PART NO.	250037MB003GX12ZL
PRODUCT SPEC.		250037MBXXXXX12ZL	
FILE NAME.	D TING	250037MB003GX12ZL-C	
SCALE	4:1	UNIT: mm	A4 SHEET: 1 of 2

ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	DESIGN	DATE
EC1BE-110505-05	B	11'/05/05	C1: 版次變更	謝小勇	李清松	General	謝小勇	15'/06/03
EC1B-070412-11	A	07'/04/12	B1: 變更包材結構	謝昌林	陳新杰	Angle	楊國輝	15'/06/03
	0	07'/01/12	A1: ADD 電鍍系列表 A2: 增加下壓行程彈力標註 A3: 變更端子材質 C5210H(日本鍍)-C1990.	張松雷	簡士鈞	X±0.25	李清泉	15'/06/03
			NEW RELEASE	蔣武向	葉銘良	.X±0.20		
						.XX±0.15		
						.XXX±0.08		